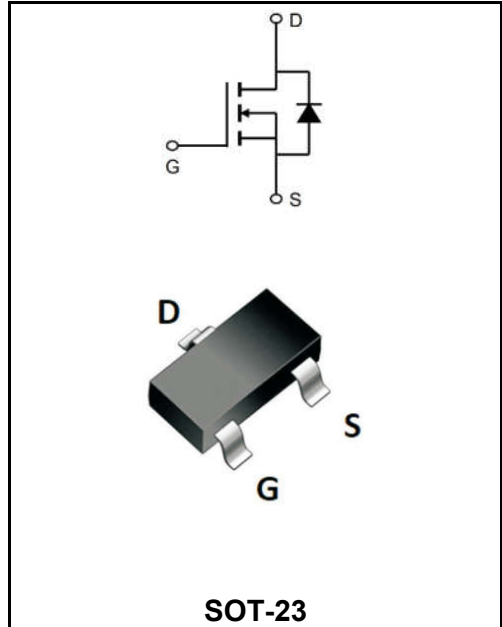


20V N-CHANNEL ENHANCEMENT MODE MOSFET

MAIN CHARACTERISTICS

| | |
|---|----------------------------|
| I_D | 4.5A |
| V_{DSS} | 20V |
| R_{DS(on)-typ(@V_{GS}=4.5V)} | < 30mΩ (Type:22 mΩ) |



Application

- ◆ Battery protection
- ◆ Load switch
- ◆ Uninterruptible power supply



Product Specification Classification

| Part Number | Package | Marking | Pack |
|-------------|---------|---------|--------------|
| YFW2300A | SOT-23 | 2300 | 3000PCS/Tape |

Maximum Ratings at Tc=25°C unless otherwise specified

| Characteristics | Symbols | Value | Units |
|---|------------------------|-------------|-------------|
| Drain-Source Voltage | V_{DS} | 20 | V |
| Gate - Source Voltage | V_{GS} | ±12 | V |
| Continuous Drain Current, V _{GS} @ 4.5V ¹ @T _A =25°C | I_D | 4.5 | A |
| Continuous Drain Current, V _{GS} @ 4.5V ¹ @T _A =70°C | I_D | 2.8 | A |
| Pulsed Drain Current ² | I_{DM} | 14.4 | A |
| Total Power Dissipation ³ @T _A =25°C | P_D | 1 | W |
| Storage Temperature Range | T_{STG} | -55 to +150 | °C |
| Operating Junction Temperature Range | T_J | -55 to +150 | °C |
| Thermal Resistance Junction-ambient ¹ | R_{θJA} | 125 | °C/W |
| Thermal Resistance Junction Case ¹ | R_{θJC} | 80 | °C/W |

Maximum Ratings at Tc=25°C unless otherwise specified

| Characteristics | Test Condition | Symbols | Min | Typ | Max | Units |
|--|--|--------------|-----|------|------|-----------|
| Drain-Source Breakdown Voltage | $V_{GS}=0V, I_D=250\mu A$ | BV_{DSS} | 20 | 22 | - | V |
| Static Drain-Source On-Resistance ² | $V_{GS}=4.5V, I_D=3A$ | $R_{DS(ON)}$ | - | 22 | 30 | mΩ |
| | $V_{GS}=2.5V, I_D=2A$ | | - | 28 | 35 | |
| Gate -Threshold Voltage | $V_{DS}=V_{GS}, I_D=250\mu A$ | $V_{GS(th)}$ | 0.5 | 0.75 | 1.2 | V |
| Drain-Source Leakage Current | $V_{DS}=16V, V_{GS}=0V, T_J=25^\circ C$ | I_{DSS} | - | - | 1 | μA |
| | $V_{DS}=16V, V_{GS}=0V, T_J=55^\circ C$ | | - | - | 5 | |
| Gate-Source Leakage Current | $V_{GS}=\pm 12V, V_{DS}=0V$ | I_{GSS} | - | - | ±100 | nA |
| Forward Transconductance | $V_{DS}=5V, I_D=3A$ | g_{fs} | - | 10.5 | - | S |
| Total Gate Charge(4.5V) | $V_{DS}=15V$ $V_{GS}=4.5V$ $I_D=3A$ | Q_g | - | 4.6 | - | nC |
| Gate-Source Charge | | Q_{gs} | - | 0.7 | - | |
| Gate-Drain Charge | | Q_{gd} | - | 1.5 | - | |
| Turn-on delay time | $V_{DD}=10V$ $V_{GS}=4.5V$ $R_G=3.3\Omega$ $I_D=3A$ | $t_{d(on)}$ | - | 1.6 | - | ns |
| Rise Time | | T_r | - | 42 | - | |
| Turn-Off Delay Time | | $t_{d(OFF)}$ | - | 14 | - | |
| Fall Time | | t_f | - | 7 | - | |
| Input Capacitance | $V_{DS}=15V$ $V_{GS}=0V$ $f=1.0MHz$ | C_{iss} | - | 310 | - | μF |
| Output Capacitance | | C_{oss} | - | 49 | - | |
| Reverse Transfer Capacitance | | C_{rss} | - | 35 | - | |
| Continuous Source Current ^{1,4} | $V_G=V_D=0V$, Force Current | I_S | - | - | 3.6 | A |
| Diode Forward Voltage ² | $V_{GS}=0V, I_S=1A, T_J=25^\circ C$ | V_{SD} | - | - | 1.2 | V |

Note :

- 1、 The data tested by surface mounted on a 1 inch2 FR-4 board with 2OZ copper.
- 2、 The data tested by pulsed , pulse width $\cong 300\mu s$, duty cycle $\cong 2\%$
- 3、 The power dissipation is limited by 150°C junction temperature
- 4、 The data is theoretically the same as ID and IDM , in real applications , should be limited by total power dissipation.

Ratings and Characteristic Curves

Typical Characteristics

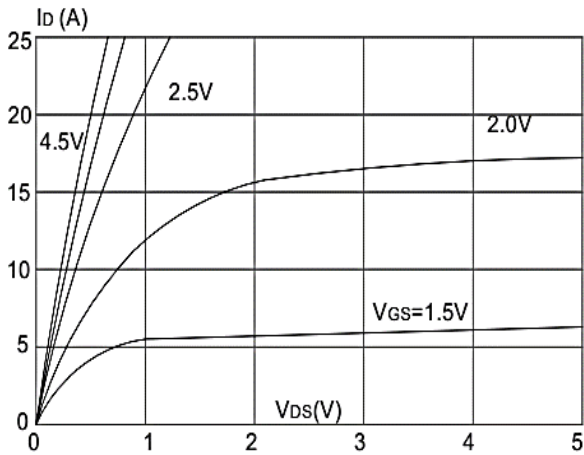


Figure 1: Output Characteristics

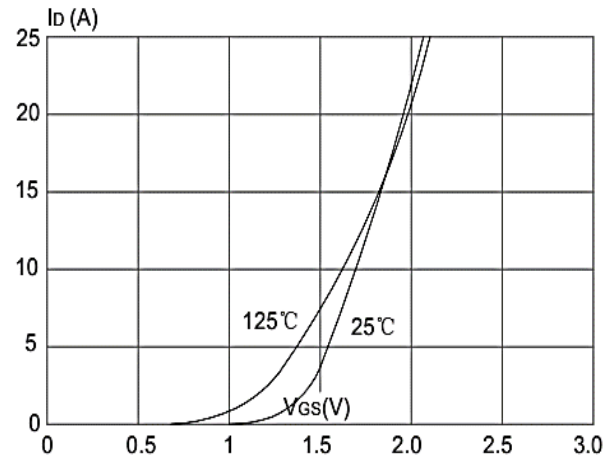


Figure 2: Typical Transfer Characteristics

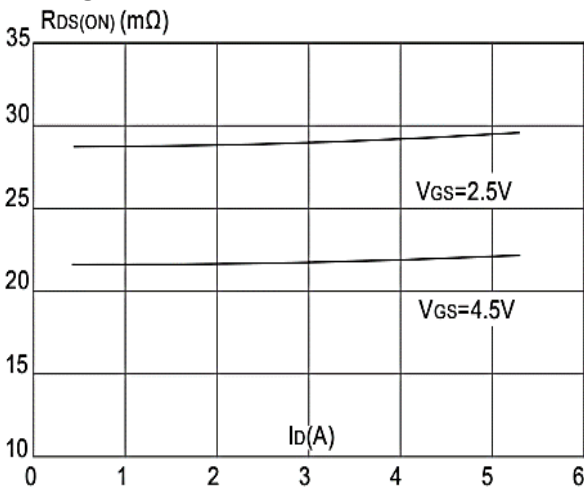


Figure 3: On-resistance vs. Drain Current

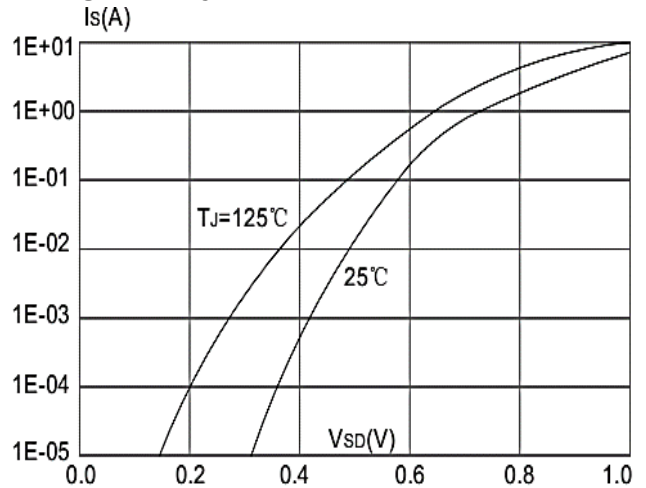


Figure 4: Body Diode Characteristics

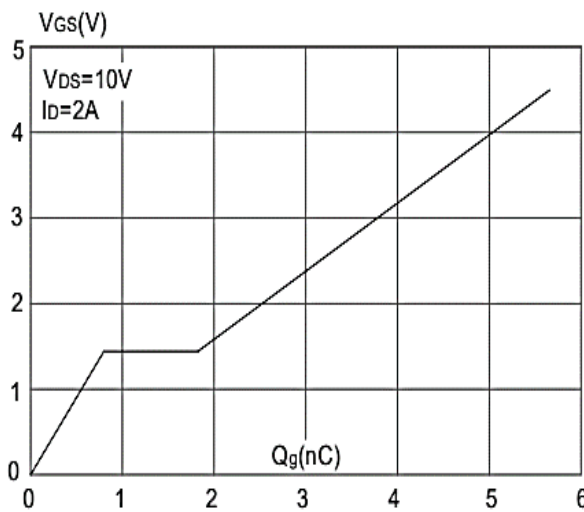


Figure 5: Gate Charge Characteristics

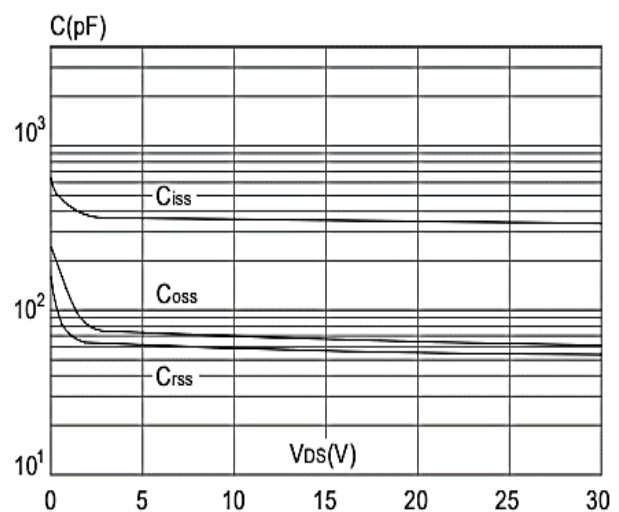


Figure 6: Capacitance Characteristics

Ratings and Characteristic Curves

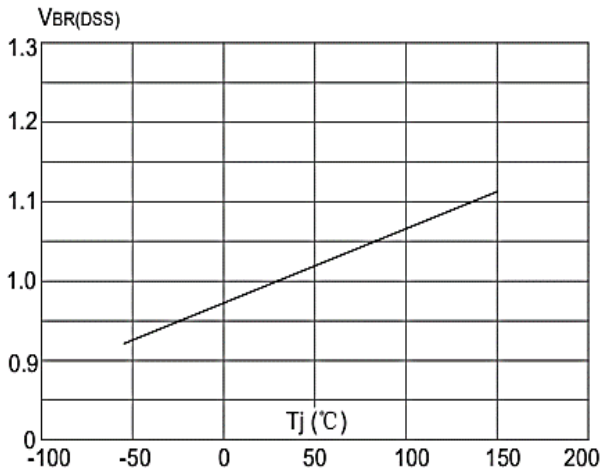


Figure 7: Normalized Breakdown Voltage vs Junction Temperature

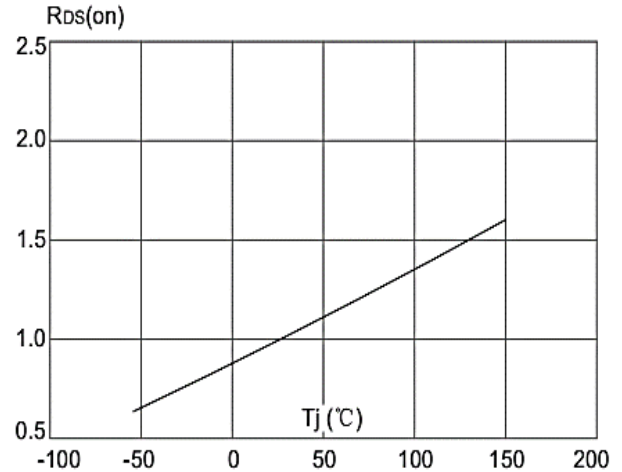


Figure 8: Normalized on Resistance vs. Junction Temperature

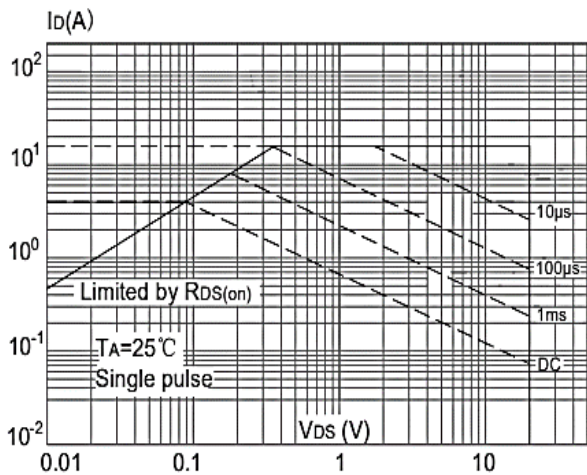


Figure 9: Maximum Safe Operating Area

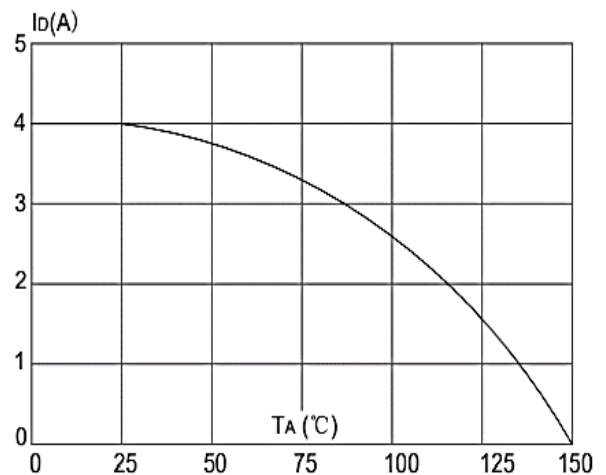


Figure 10: Maximum Continuous Drain Current vs. Ambient Temperature

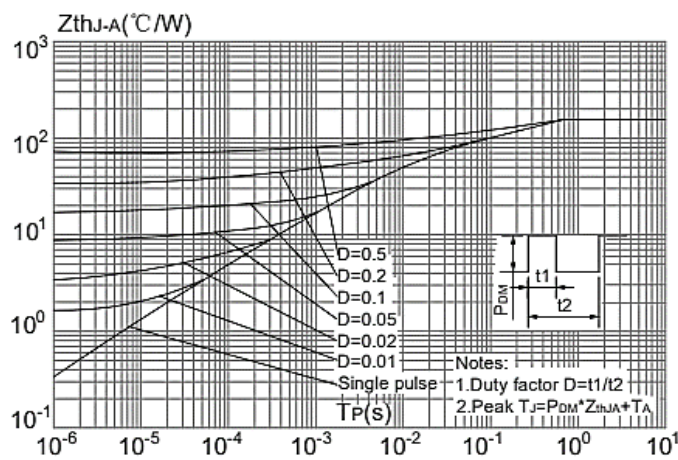
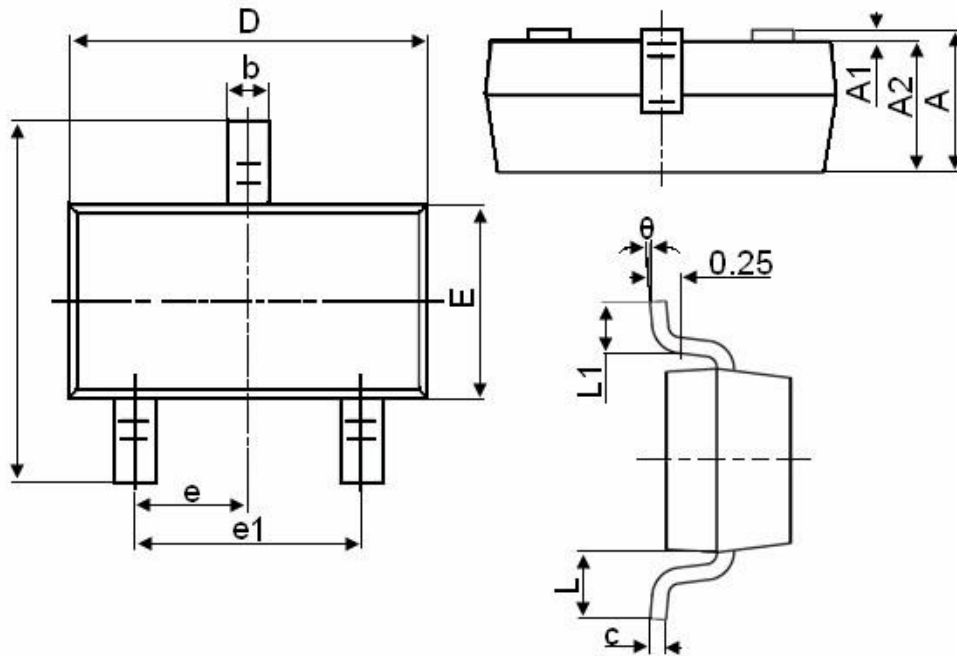


Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Ambien

SOT-23



| Symbol | Dimensions in Millimeters | |
|--------|---------------------------|-------|
| | MIN. | MAX. |
| A | 0.900 | 1.150 |
| A1 | 0.000 | 0.100 |
| A2 | 0.900 | 1.050 |
| b | 0.300 | 0.500 |
| c | 0.080 | 0.150 |
| D | 2.800 | 3.000 |
| E | 1.200 | 1.400 |
| E1 | 2.250 | 2.550 |
| e | 0.950TYP | |
| e1 | 1.800 | 2.000 |
| L | 0.550REF | |
| L1 | 0.300 | 0.500 |
| θ | 0° | 8° |